

FIG. 2

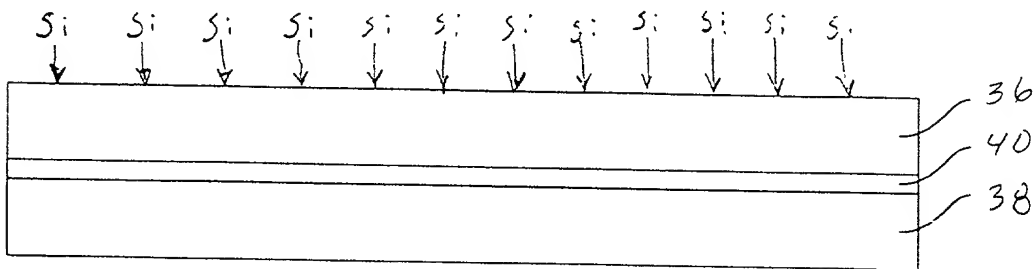


FIG. 3

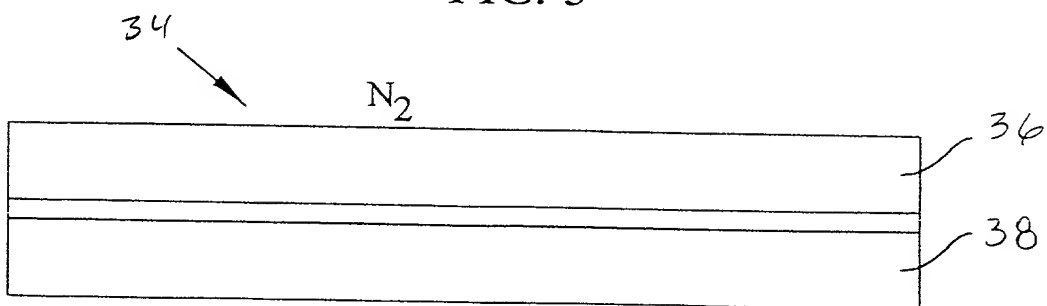


FIG. 4

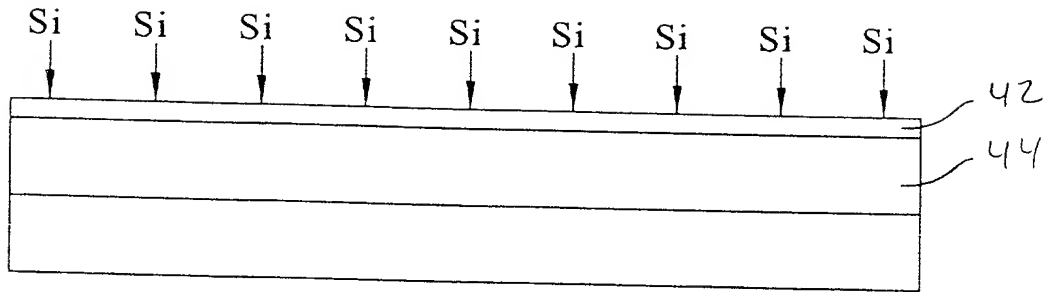


FIG. 5

N₂ ANNEAL

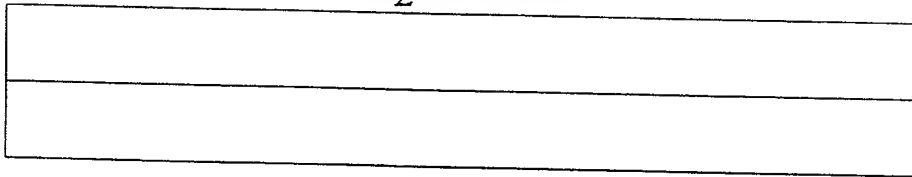


FIG. 6

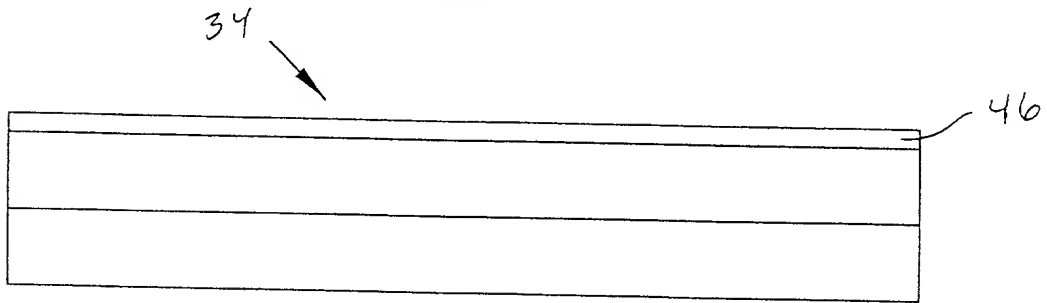


FIG. 7

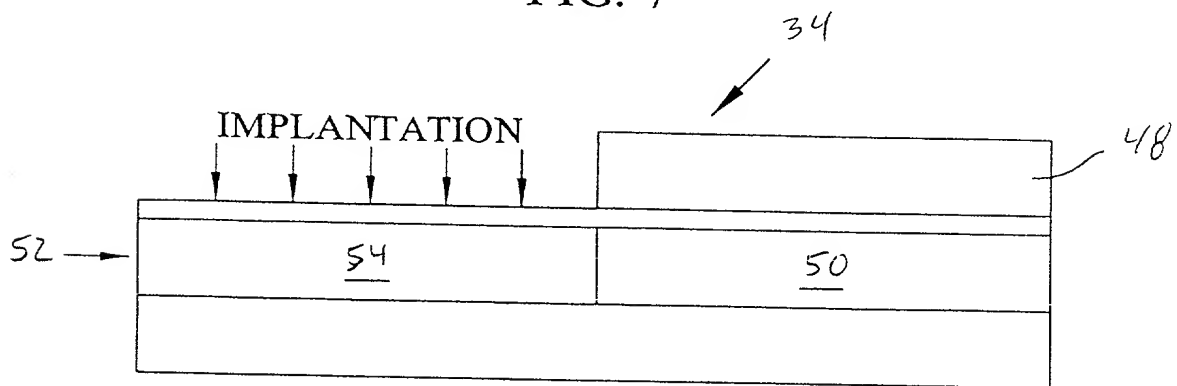


FIG. 8

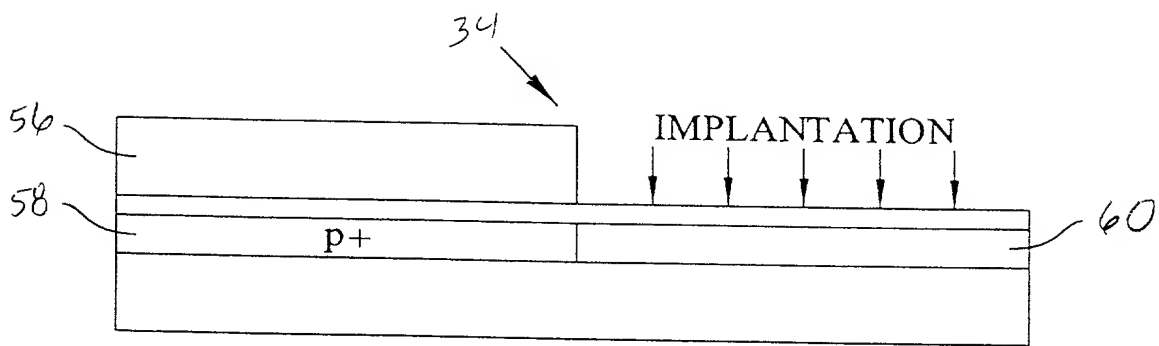


FIG. 9

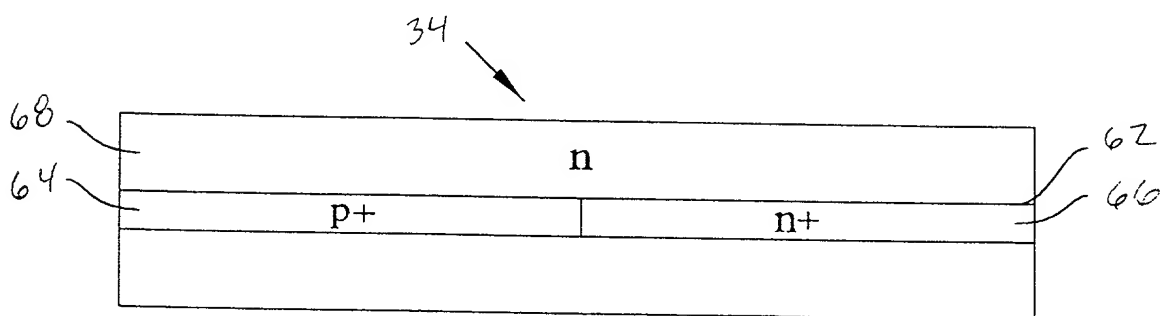


FIG. 10

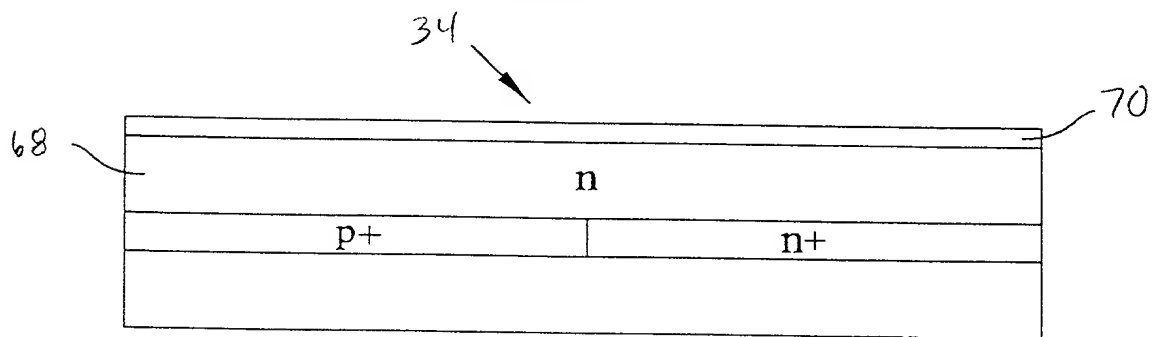


FIG. 11

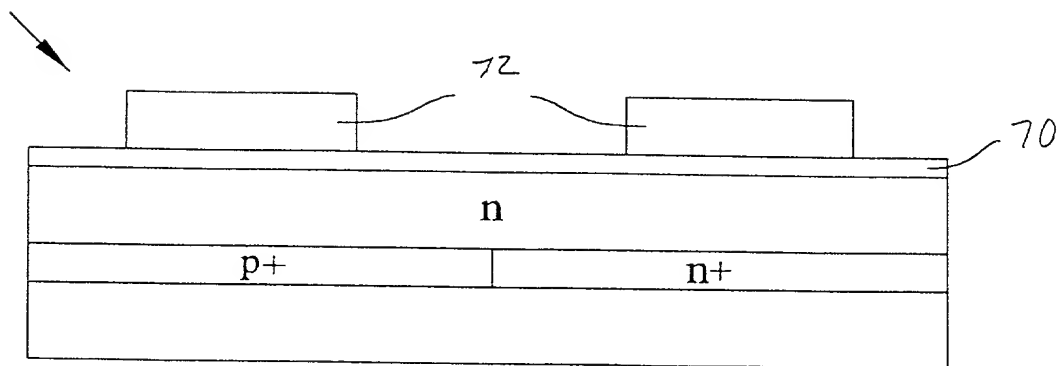


FIG. 12

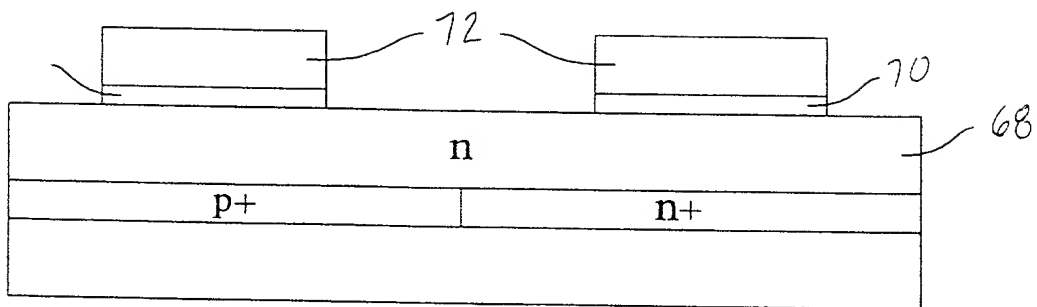


FIG. 13

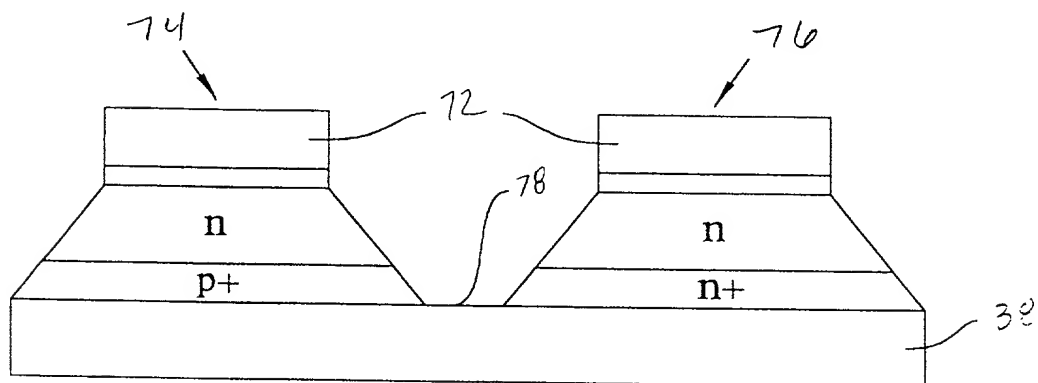


FIG. 14

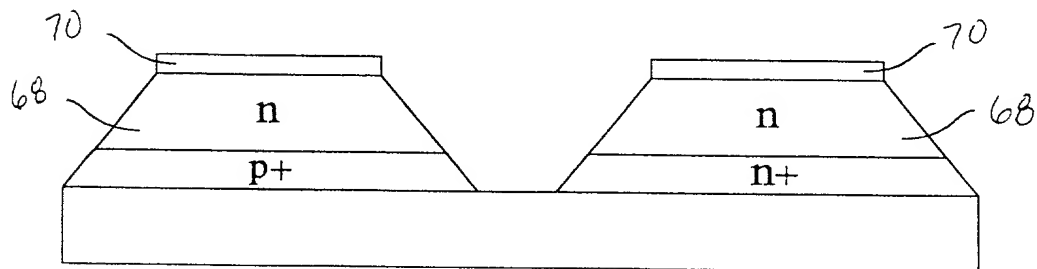


FIG. 15

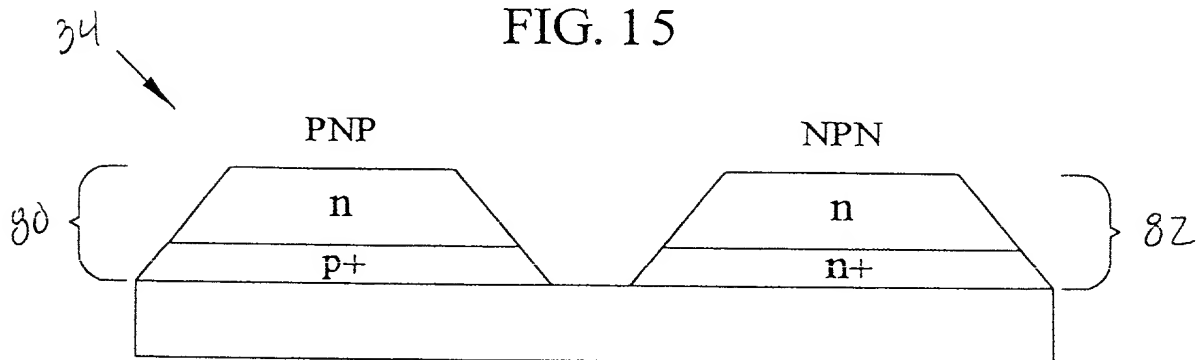


FIG. 16

34

875°C IN N₂

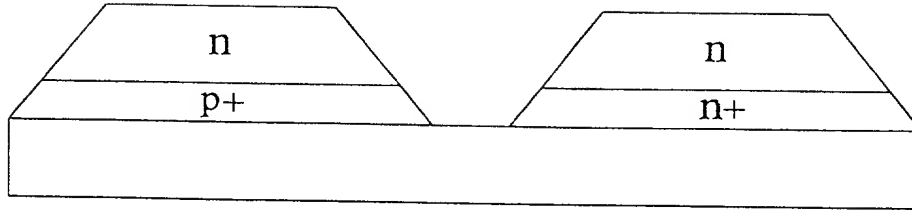


FIG. 17

34

N₂ + H₂ + O₂

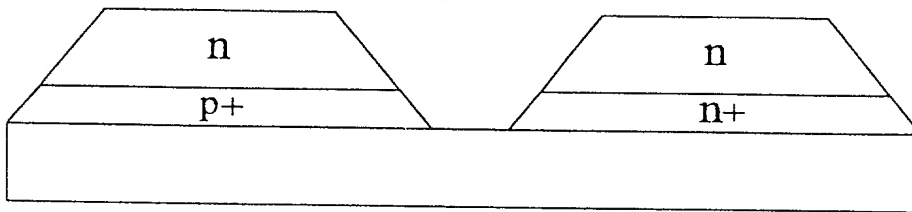


FIG. 18

34

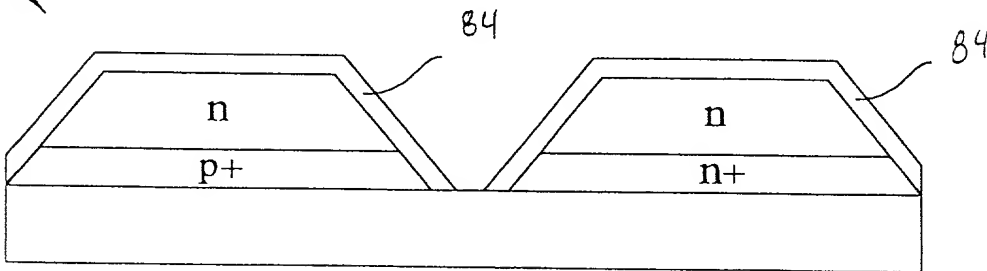


FIG. 19

34

IMPLANTATION

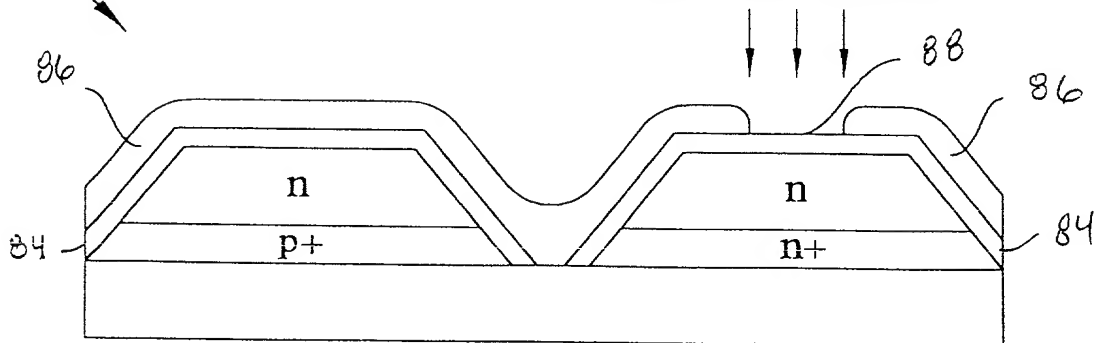


FIG. 20

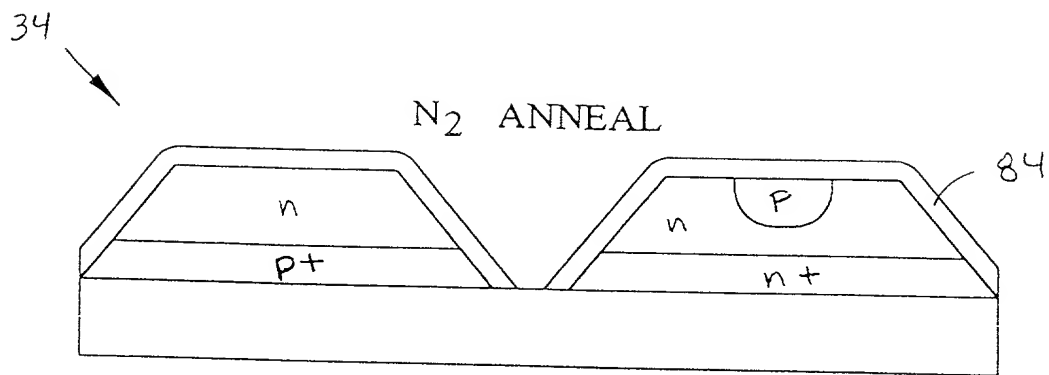


FIG. 21

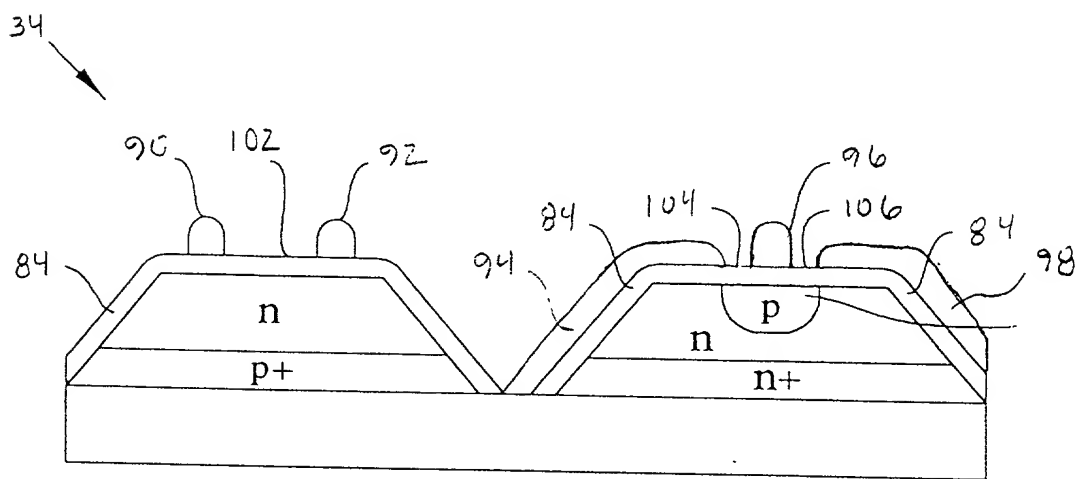


FIG. 22

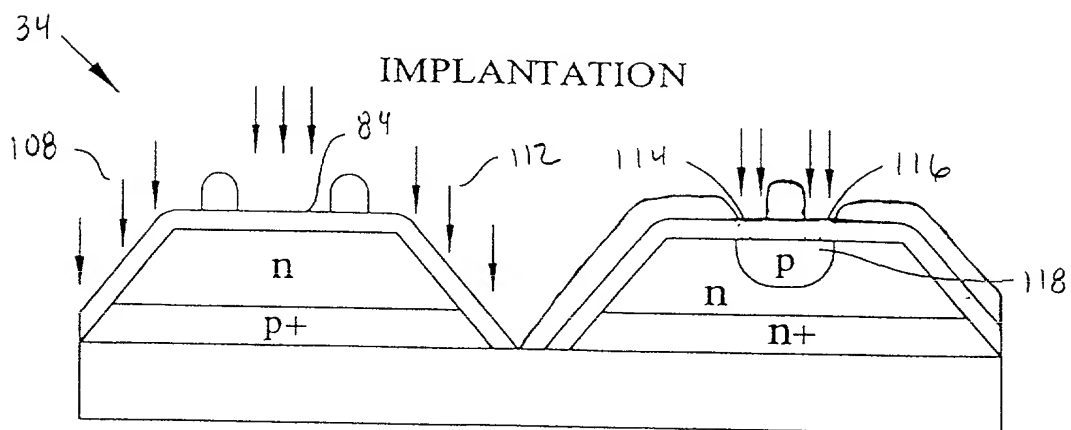


FIG. 23

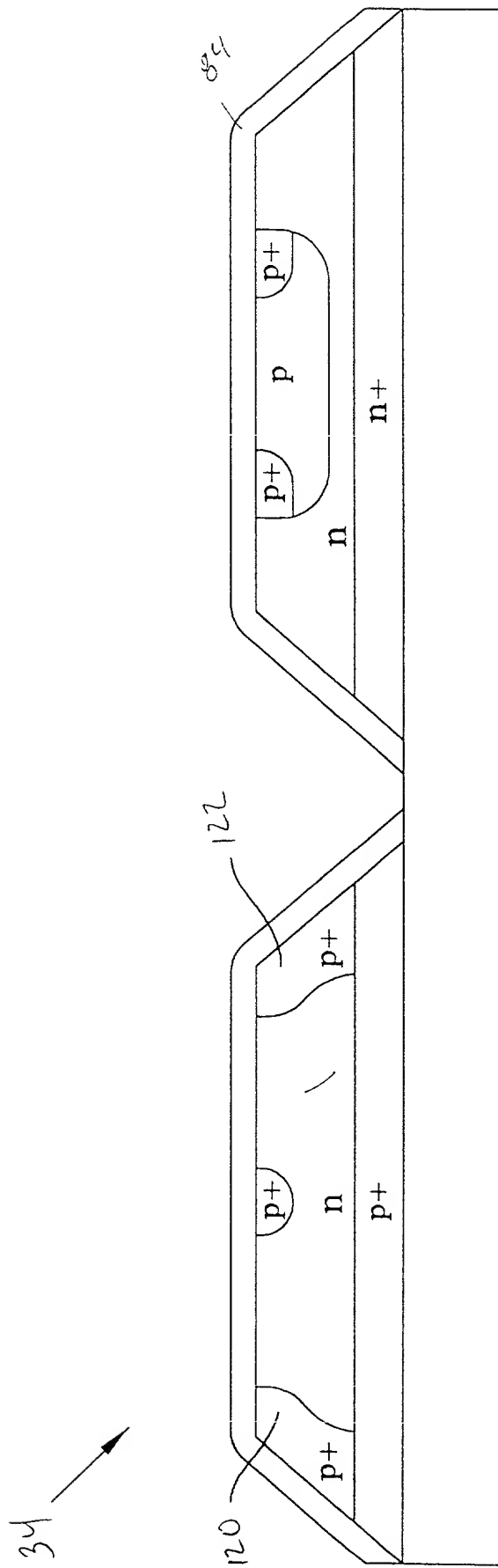


FIG. 24

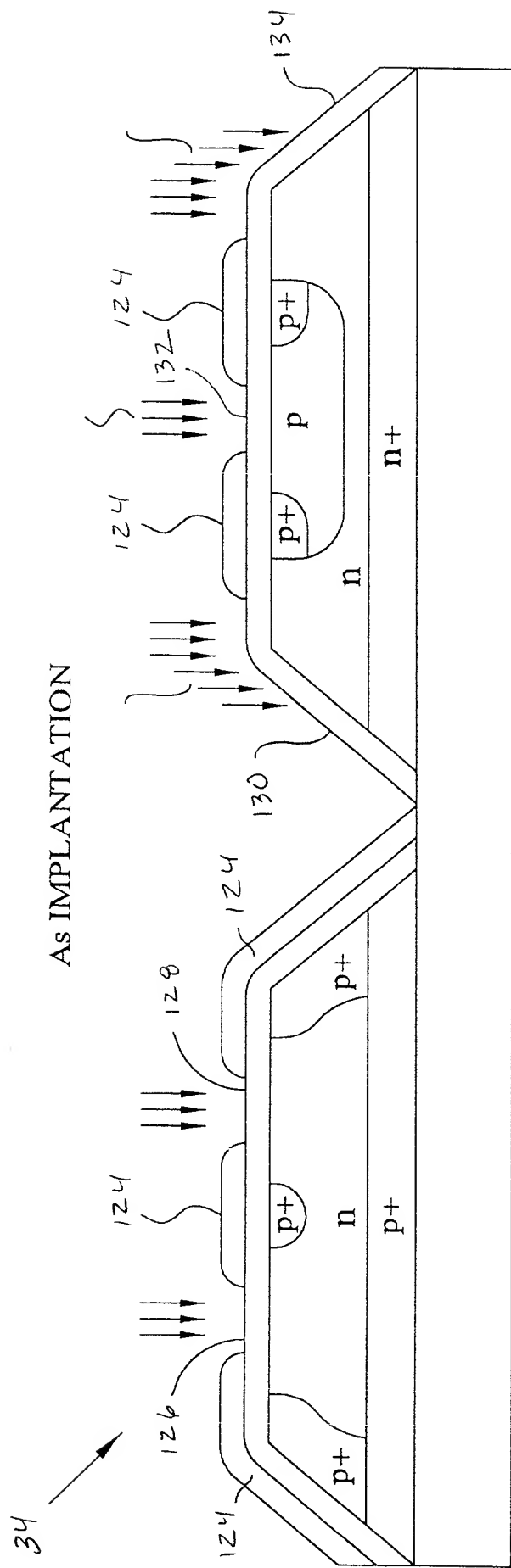


FIG. 25

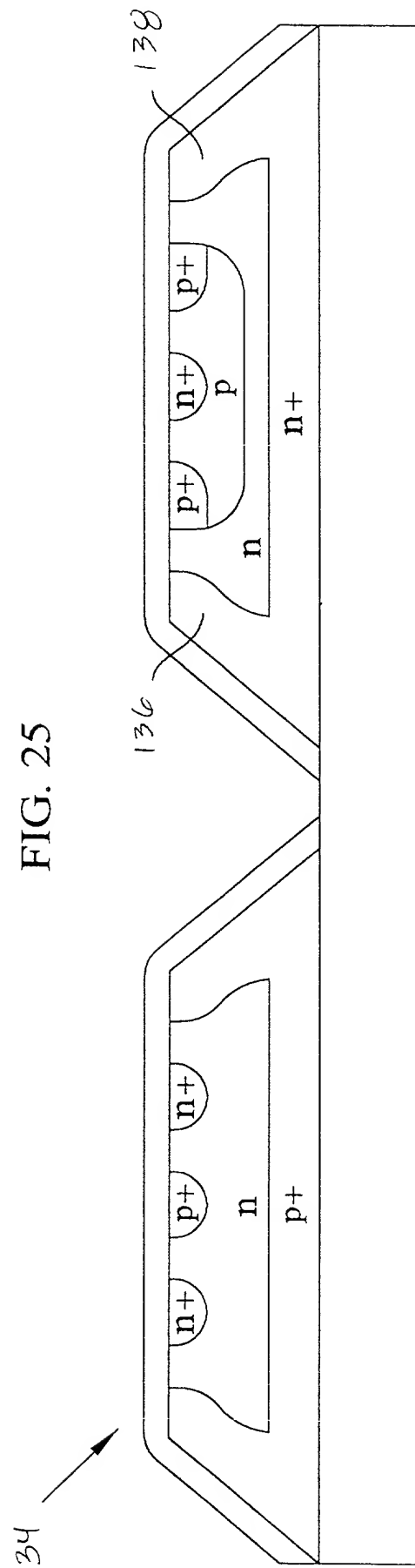


FIG. 26

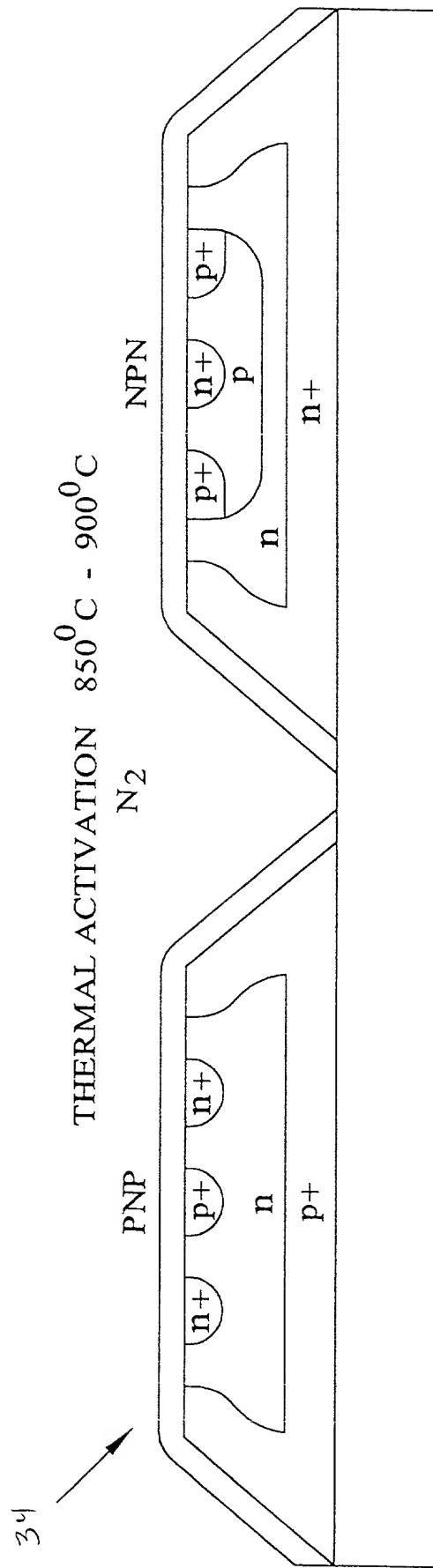


FIG. 27

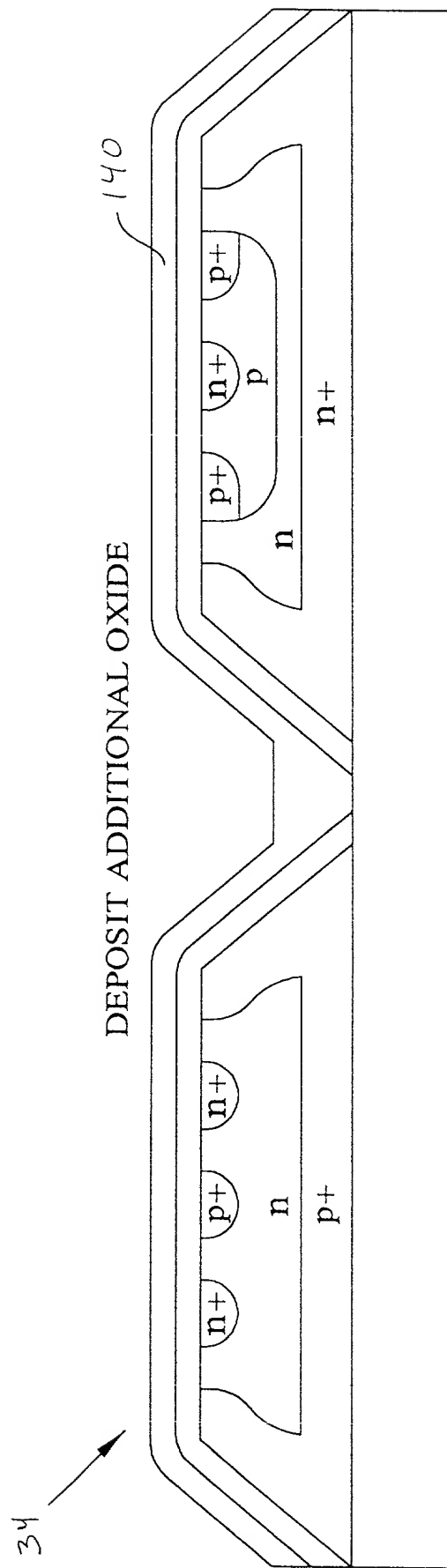


FIG. 28

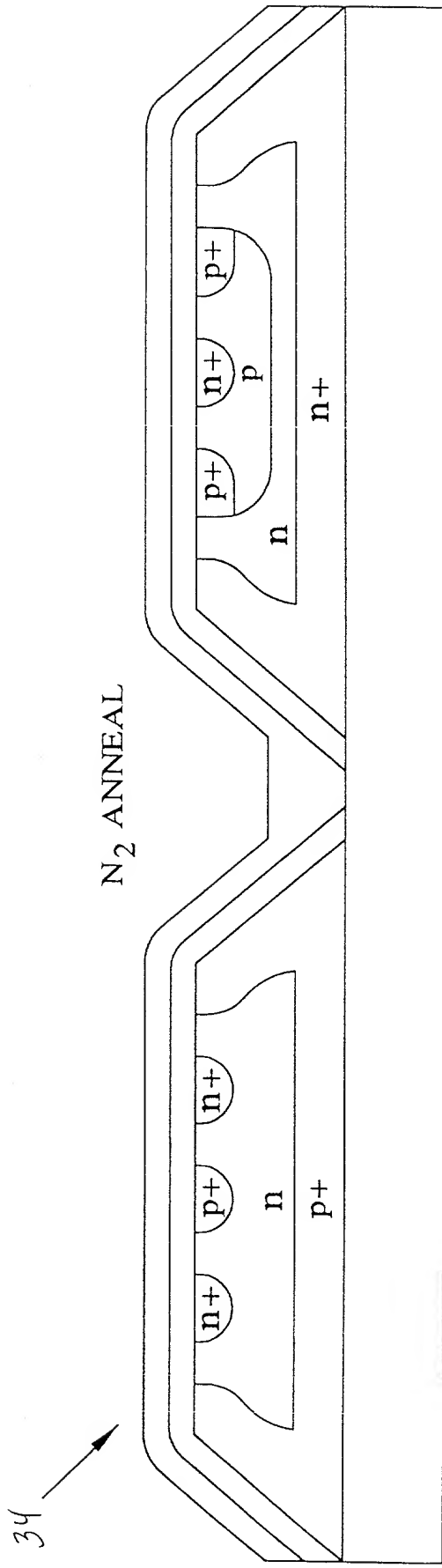


FIG. 29

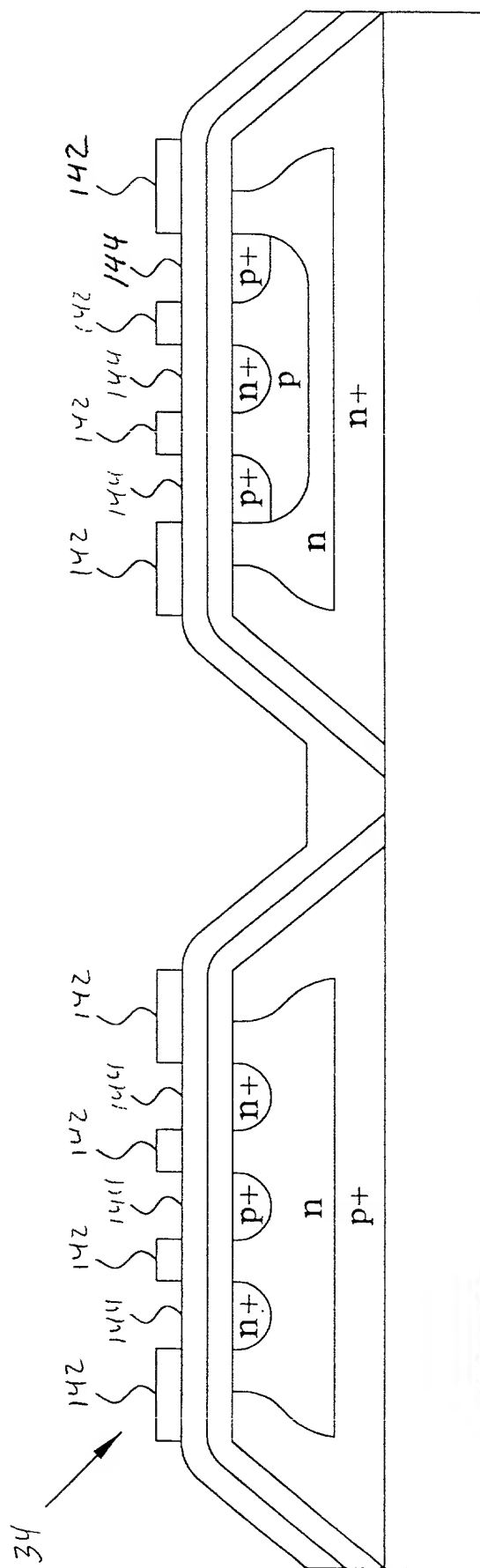


FIG. 30

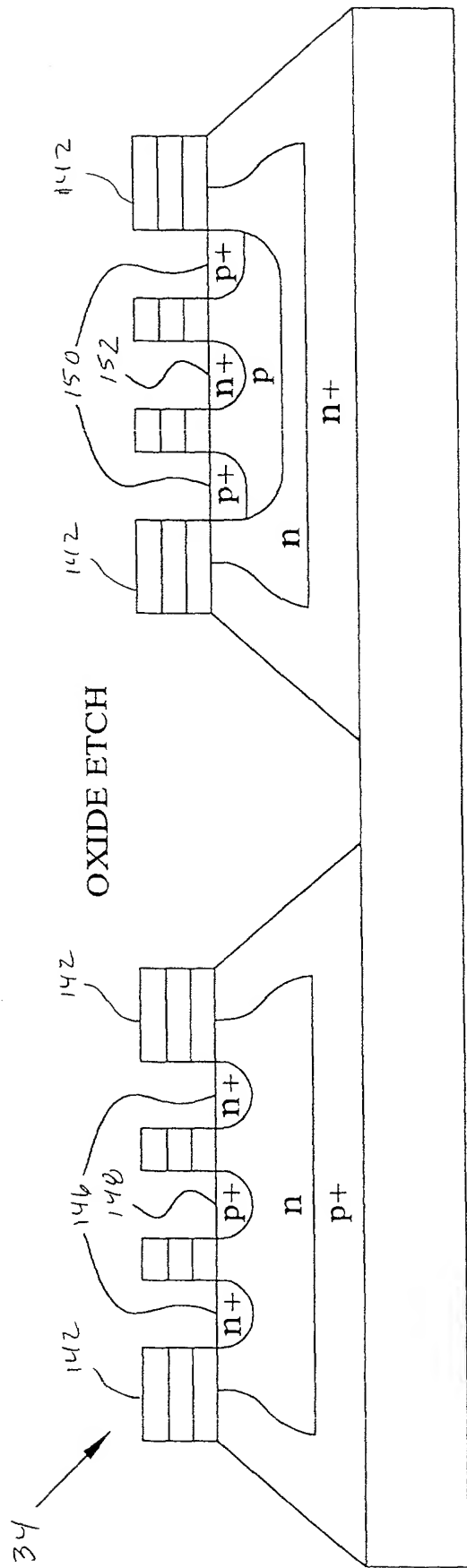


FIG. 31

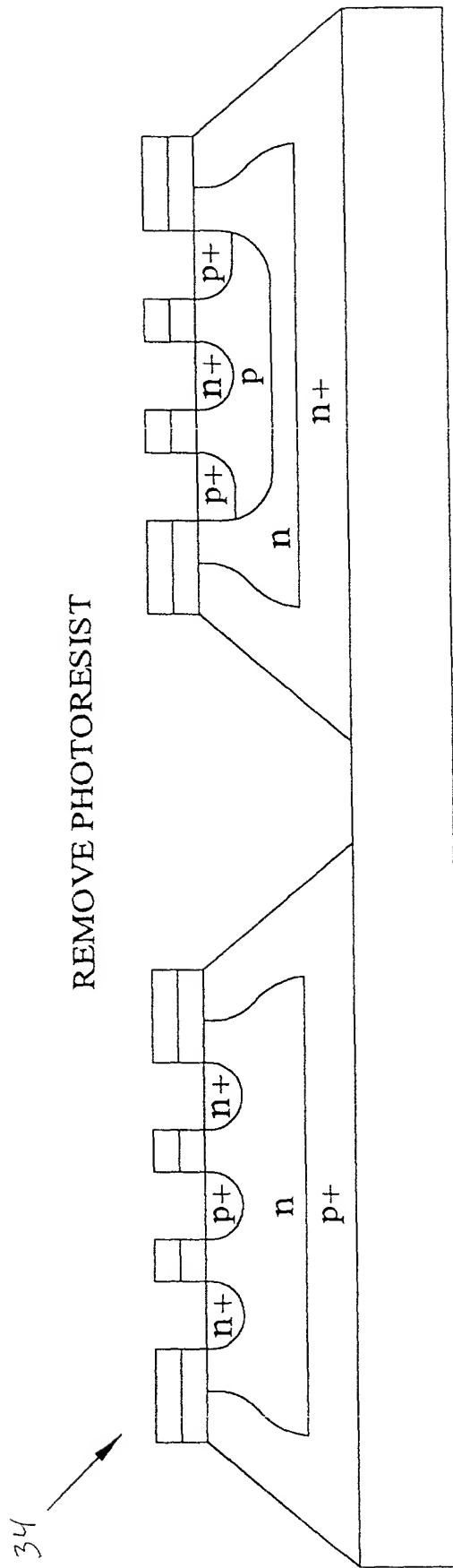


FIG. 32

34

DEPOSIT CONDUCTIVE METAL

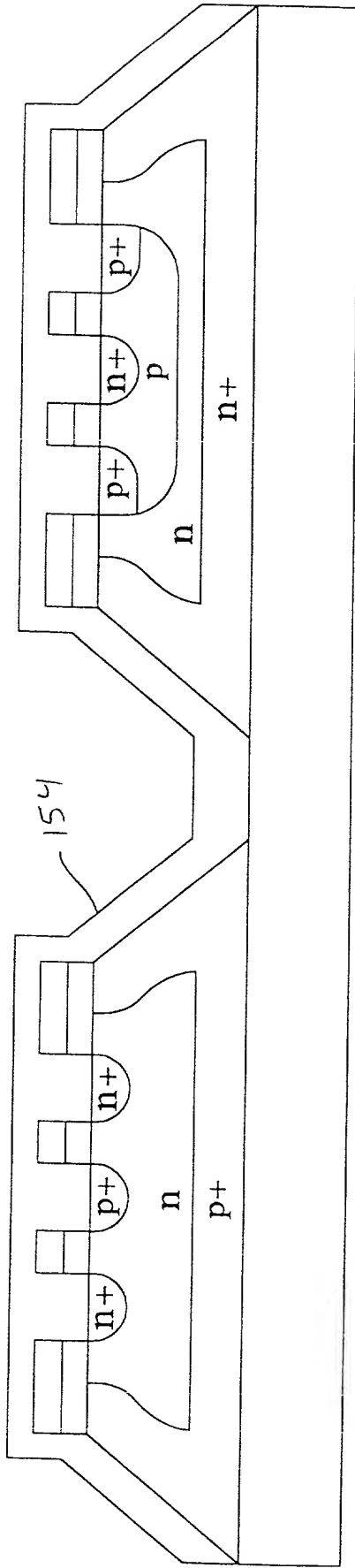


FIG. 33

34

PATTERN METAL FOR OHMIC CONTACT

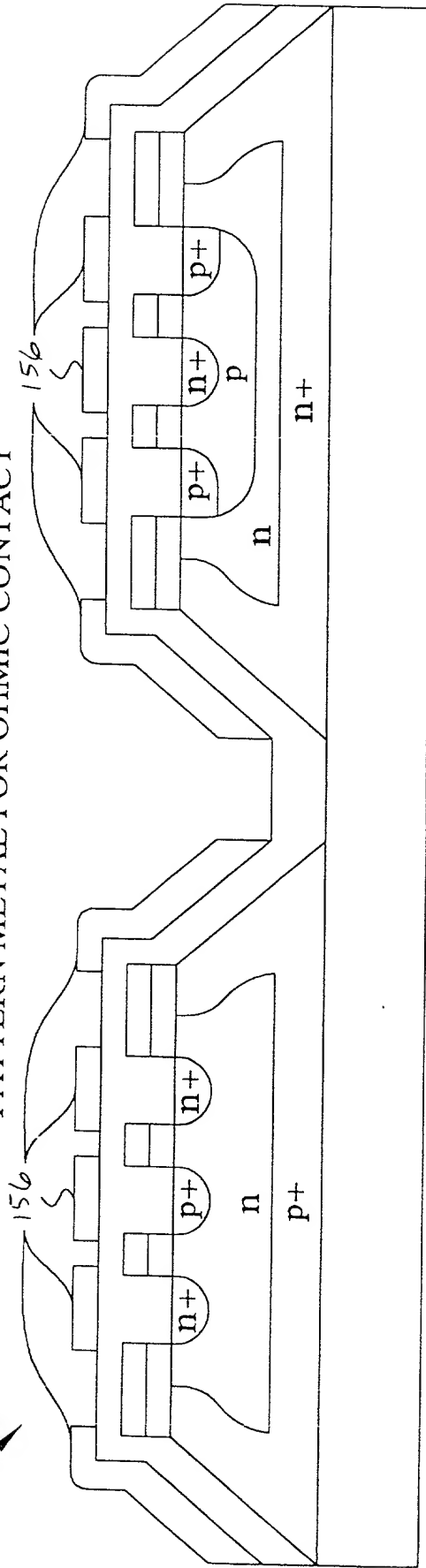


FIG. 34

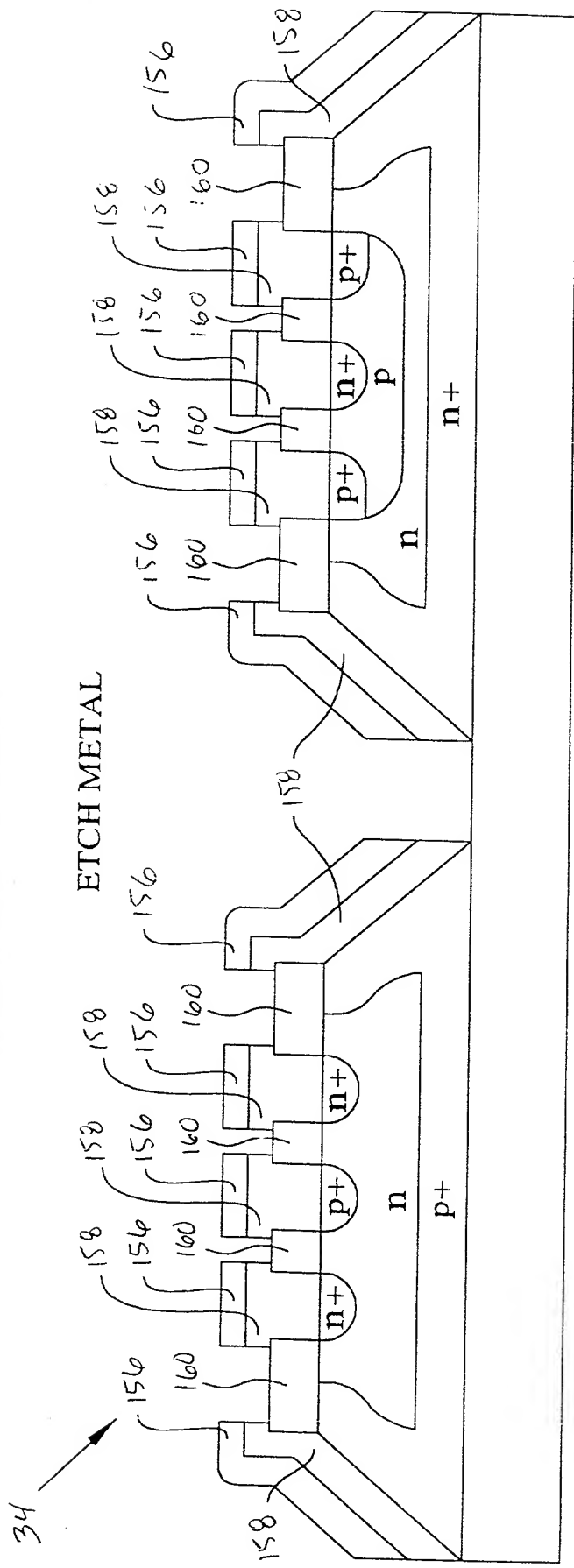


FIG. 35

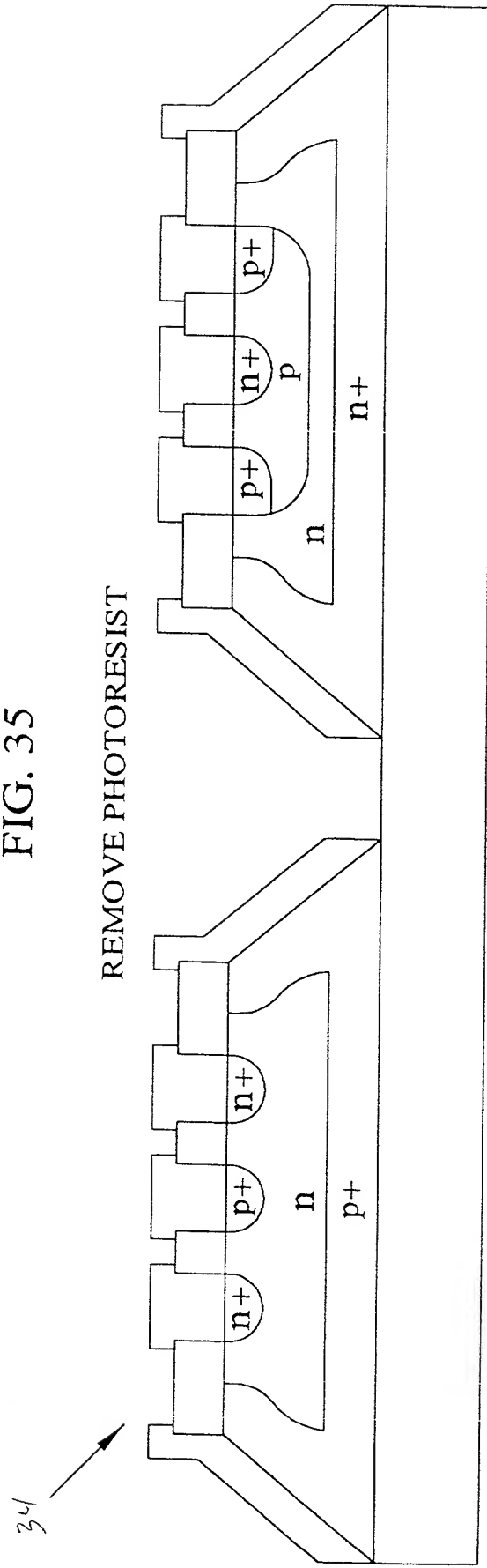


FIG. 36

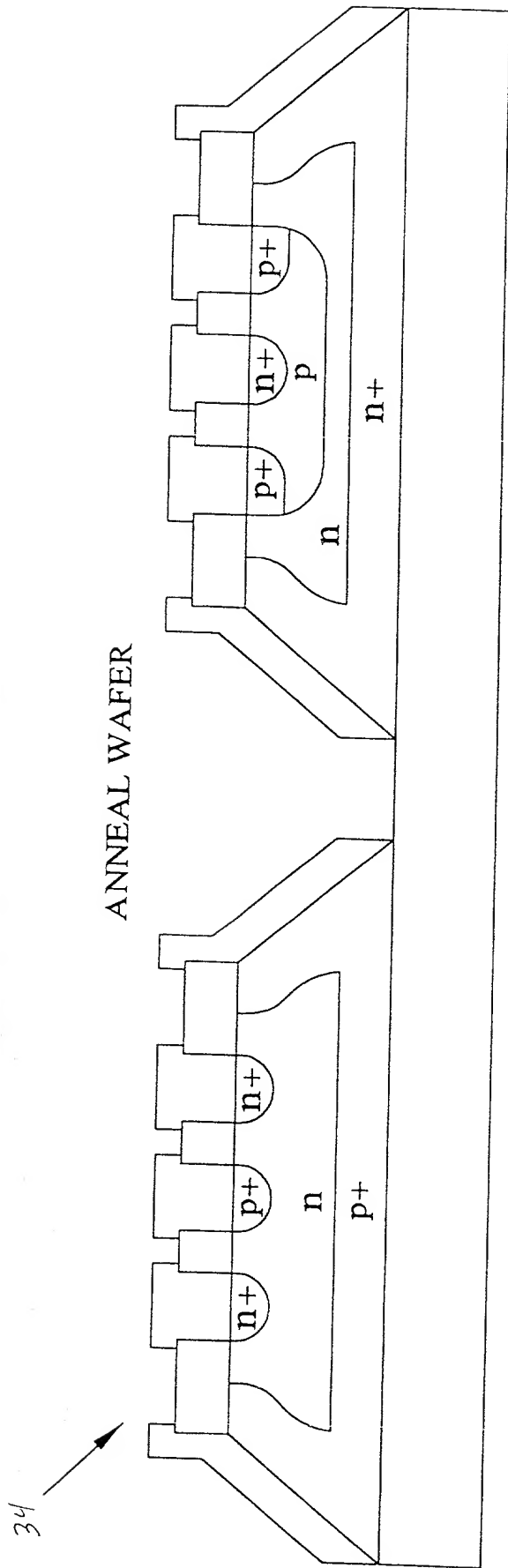


FIG. 37

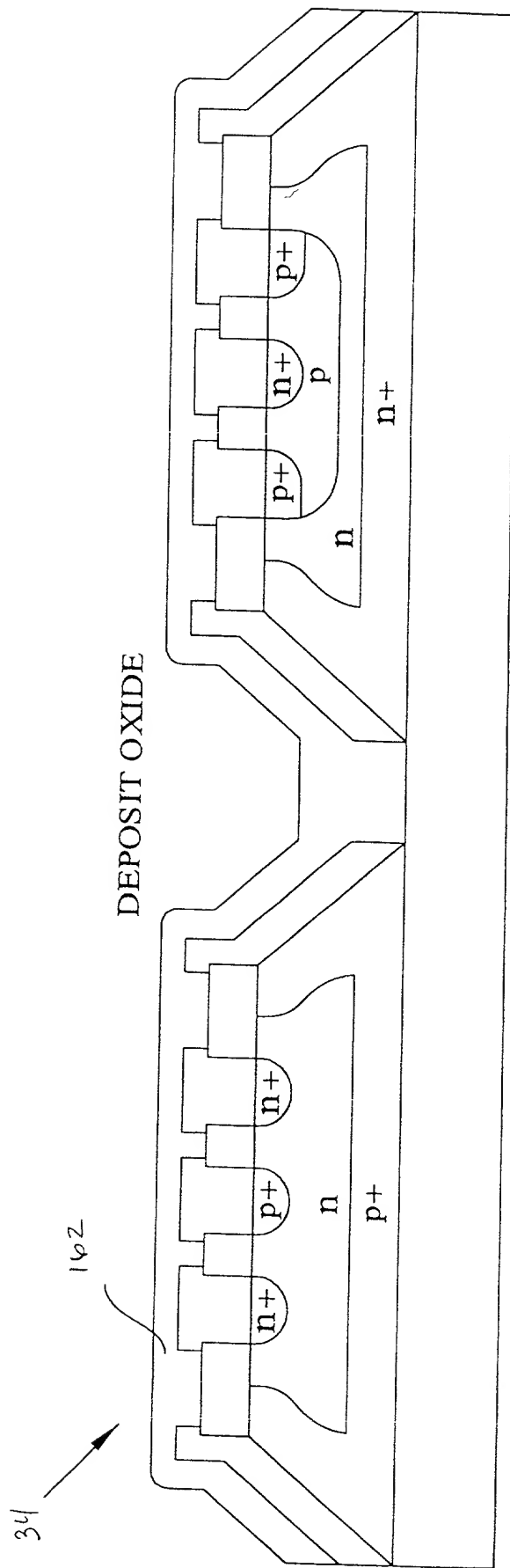


FIG. 38

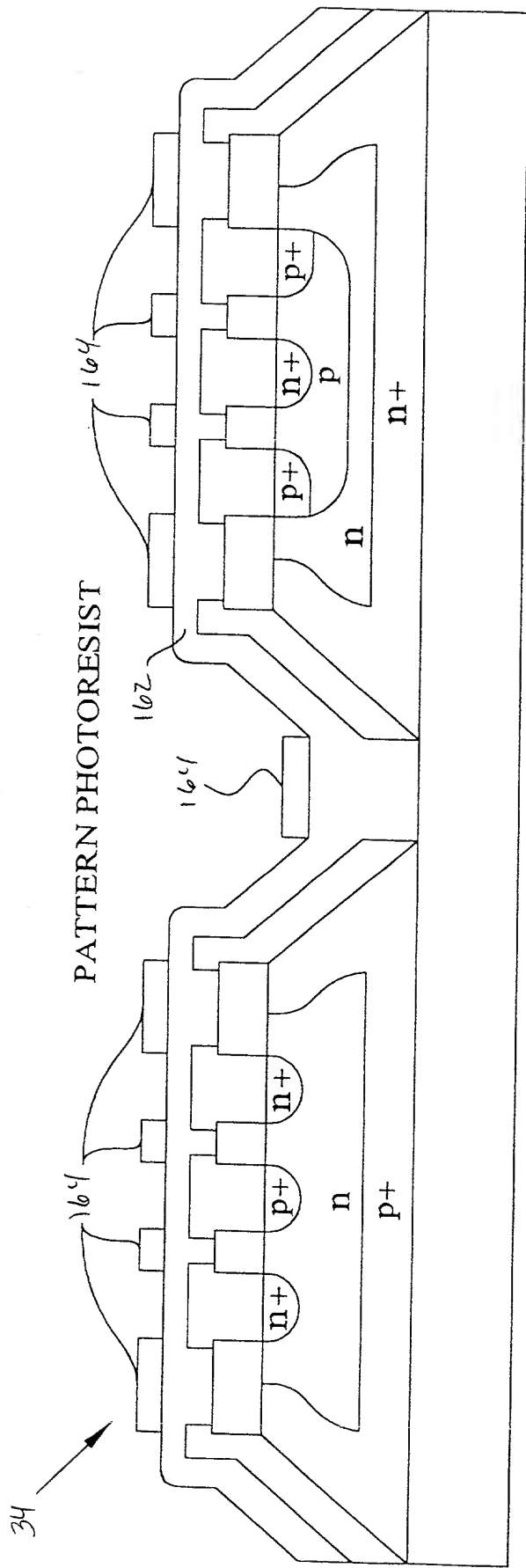


FIG. 39

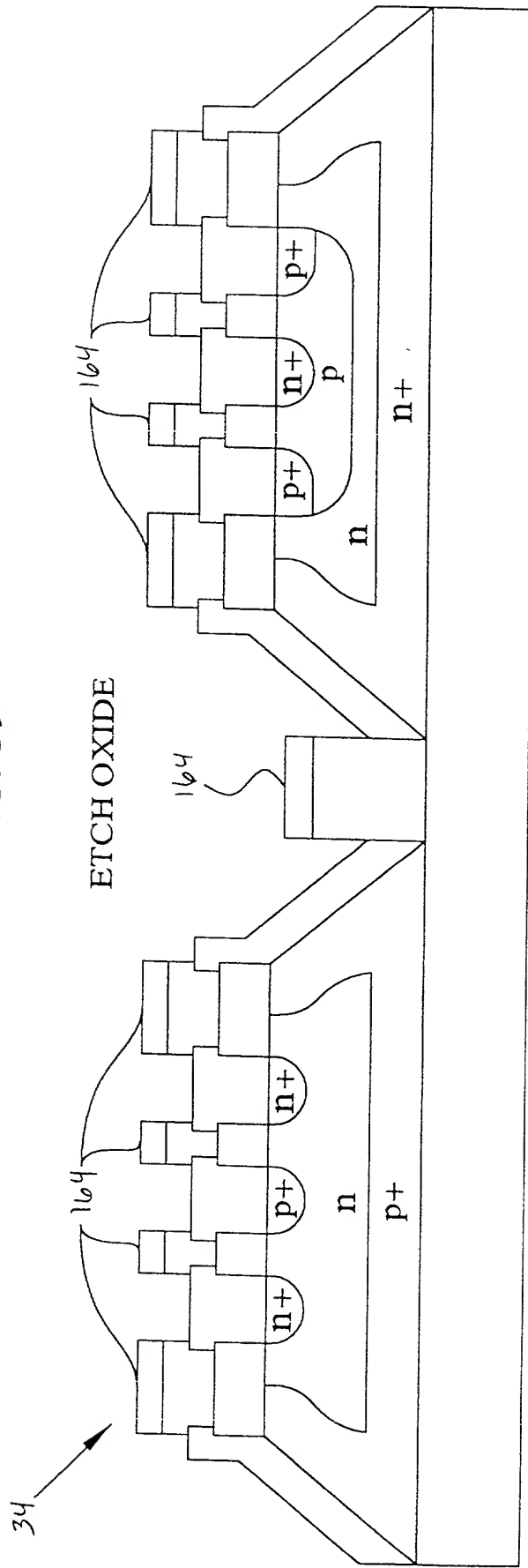


FIG. 40

34

REMOVE PHOTORESIST

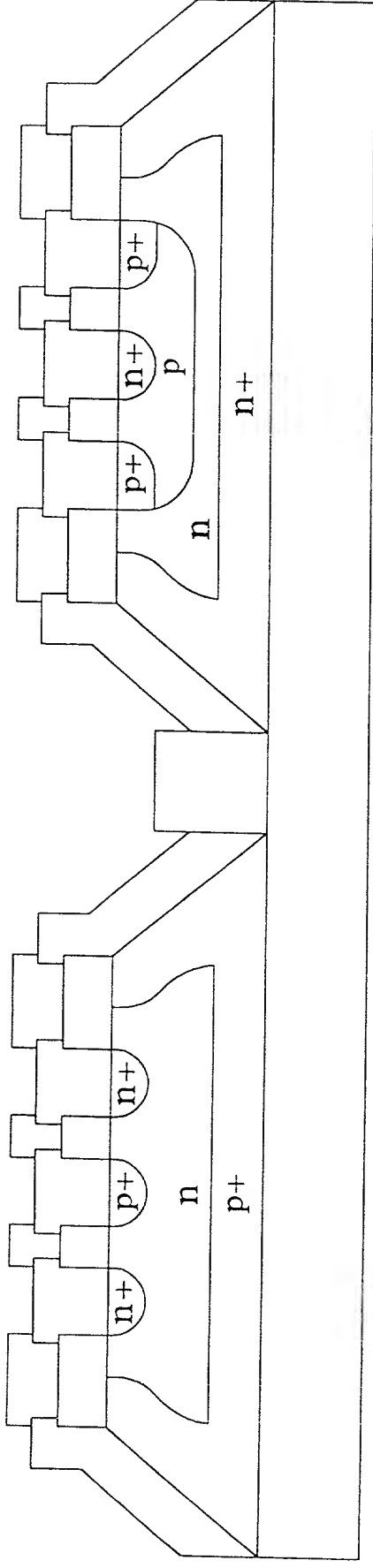
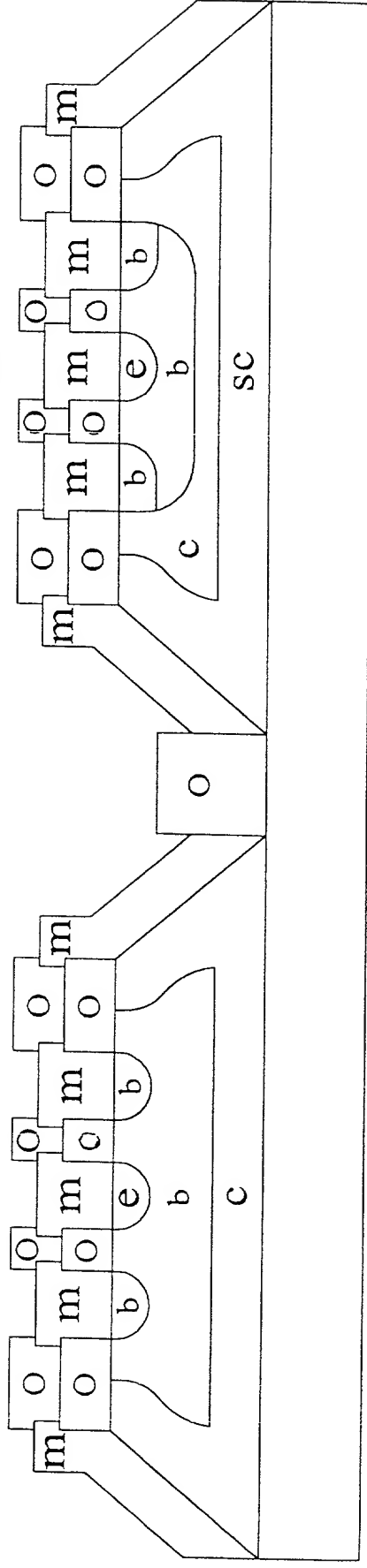


FIG. 41

10

PNP

NPN



KEY: m = metal o = oxide
e = emitter

FIG. 42